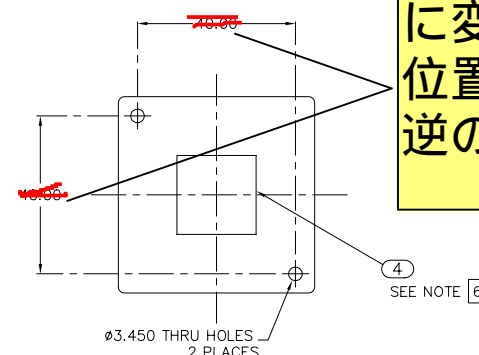
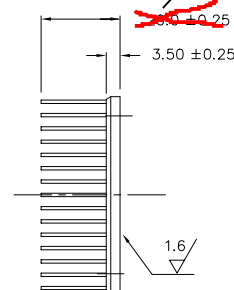
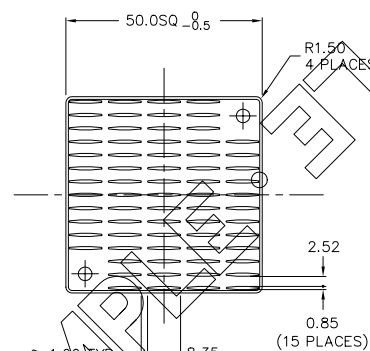


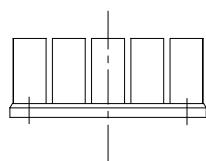
全高 15.0mm 以下

取付ピッチ 44.0x44.0
に変更。
位置は中心線に対して
逆の位置。



PCB 厚 2.40 mm
チップ高さ 2.20-2.46 mm
チップ接触面 27.0 mm x 27.0 mm
チップサイズ 35.0 mm x 35.0 mm

目標荷重 5.0 kgf



NOTES : UNLESS OTHERWISE SPECIFIED

1. INTERPRET DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M

2. ALL DIMENSIONS ARE IN MILLIMETERS [INCHES].

3. TOLERANCES : .XX ±0.254 [.010]
 .XXX ±0.127 [.005]
 ANGLES ± 1°

4. REMOVE ALL BURRS AND BREAK SHARP EDGES.
UNSPECIFIED CORNER R0.5 MAX OR C0.5 MAX

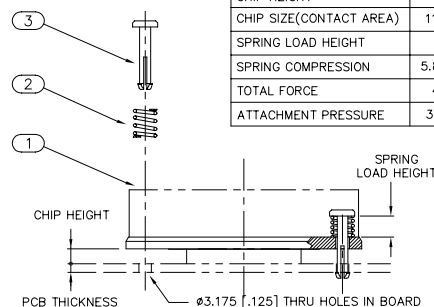
5. A BEND OF THE FIN: THE FINS MUST NOT CONTACT.

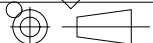
6. PEEL ONE SIDE OF LINER FROM THERMAL PAD.

ADHERE IN APPROXIMATE POSITION OF THE BASE SURFACE CENTER

ASSEMBLY IMAGE (REFERENCE ONLY) ✓ DO NOT SCALE

	Dimension
PCB THICKNESS	1.6 mm
CHIP HEIGHT	3.85 mm
CHIP SIZE(CONTACT AREA)	11.6 x 14.1 mm
SPRING LOAD HEIGHT	5.35 mm
SPRING COMPRESSION	5.85 mm (77.0%)
TOTAL FORCE	4.16 kgf (9.17 lbf)
ATTACHMENT PRESSURE	36.18 PSI



④	S001Z03F	<THERMAL INTERFACE> T-PCM905C-20S	Latex T-PCM905C 20 x 20 mm	1
③	S001YZ0M	<PUSH-RJN> PIP3.175x14.3	BRASS (ROHS COMPLIANT) C6801 SAN-ETU METALS BZ5 OR EQUIVALENT	2
②	S001YJ06	<SPRING>	OUTSIDE DIA: 6.15 mm WIRE DIA: .65 mm FREE LENGTH: 11.2 mm SPRING RATE: 3.487 (N/mm2) SOLID HEIGHT: 3.6 mm MATERIAL: Music Wire OR EQUIVALENT	2
①		<HEATSINK> <--HEATSINKNAME-->	MD50 SERIES HEAT SINK MODIFIED 6063 ALUMINUM BLACK ANODIZE	1
ITEM	PART NO.	PART NAME	REMARK	Q'TY
ALPHA CO.,LTD.			CSTMTR'S PART NO.	
	MATERIAL		NAME <--HEATSINK ASSEMBLY NAME-->	
SCALE 1 : 1	APPR & CHCK -----		PART NO. & DWG NO. -----	REV
DATE 2008.05.20	DSGN & DWG -----		RDCTN:	LOFF: